



QNHCHIP

QNN70N04SD

# Product Specification

**QNN70N04SD**

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40V Dual N-Channel MOSFET



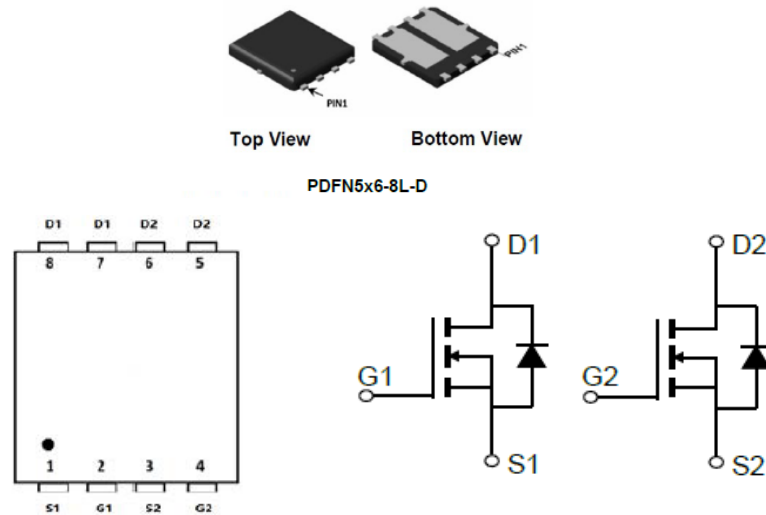
## FEATURES

- 40V, 40A  
 $R_{DS(ON)}$  TYP. = 7.6m $\Omega$  @  $V_{GS} = 10V$   
 $R_{DS(ON)}$  TYP. = 11.5m $\Omega$  @  $V_{GS} = 4.5V$
- Advanced Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead Free

## Applications

- Load Switch
- PWM Application
- Power Management

## Pin Description



NO.	Symbol	Description
1	S1	SOURCE1
2	G1	GATE1
3	S2	SOURCE2
4	G2	GATE2
5	D1	DRAIN1
6	D1	DRAIN1
7	D2	DRAIN2
8	D2	DRAIN2



## Absolute Maximum Ratings

(@  $T_C = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Value	Units	
$V_{DS}$	Drain-to-Source Voltage	40	V	
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V	
$I_D$	Continuous Drain Current	$T_C=25^\circ\text{C}$	40	A
		$T_C=100^\circ\text{C}$	25	
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	160	A	
$E_{AS}$	Single Pulsed Avalanche Energy <sup>(2)</sup>	72	mJ	
$P_D$	Power Dissipation	$T_C=25^\circ\text{C}$	114	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>(3)</sup>	45	$^\circ\text{C}/\text{W}$	
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.1		
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	$^\circ\text{C}$	



## Electrical Characteristics

(T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =250uA, V <sub>GS</sub> =0V	40	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V	-	-	1.0	uA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	1.1	1.6	2.4	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(4)</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =30A	-	7.6	8.5	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	11.5	14.0	mΩ
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =20V, f=1MHz	-	1209	-	pF
C <sub>oss</sub>	Output Capacitance		-	167	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	153	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> =0~10V, V <sub>DS</sub> =20V, I <sub>D</sub> =20A	-	48	-	nC
Q <sub>gs</sub>	Gate Source Charge		-	10	-	nC
Q <sub>gd</sub>	Gate Drain("Miller") Charge		-	10	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> =10V, V <sub>DD</sub> =20V, I <sub>D</sub> =20A, R <sub>GEN</sub> =3Ω	-	10	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	28	-	ns
t <sub>d(off)</sub>	Turn-Off DelayTime		-	40	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	7	-	ns
<b>Drain-Source Diode Characteristics and Max Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	40	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	160	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =30A	-	-	0.7	V
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =20A, di/dt=100A/us	-	11	-	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge		-	5	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. E<sub>AS</sub> condition: Starting T<sub>J</sub>=25°C, V<sub>DD</sub>=20V, V<sub>G</sub>=10V, R<sub>G</sub>=25Ω, L=0.5mH, I<sub>AS</sub>=17A
3. R<sub>θJA</sub> is measured with the device mounted on a 1 inch<sup>2</sup> pad of 2oz copper FR4 PCB
4. Pulse Test: Pulse Width≤300us, Duty Cycle≤0.5%.



# Typical Performance Characteristics

Figure 1: Output Characteristics

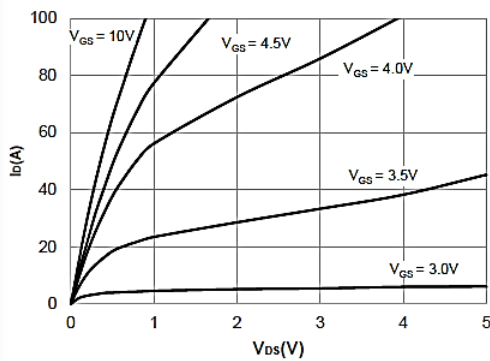


Figure 2: Typical Transfer Characteristics

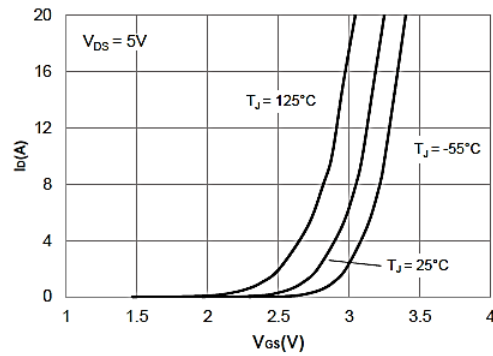


Figure 3: On-resistance vs. Drain Current

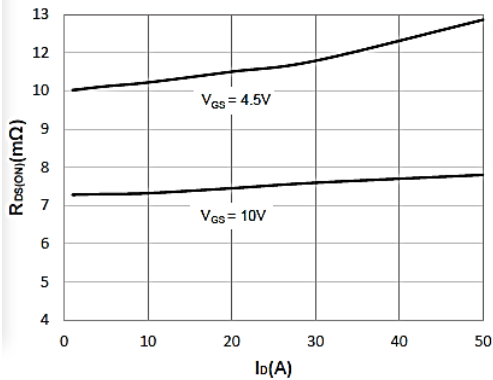


Figure 4: Body Diode Characteristics

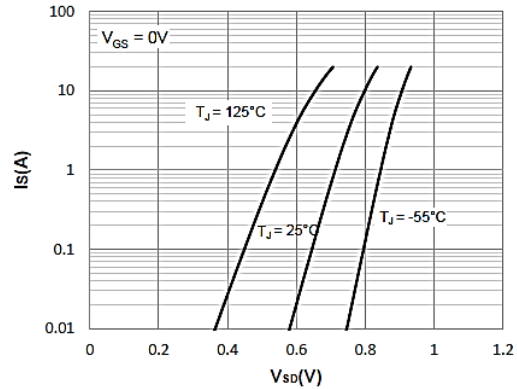


Figure 5: Gate Charge Characteristics

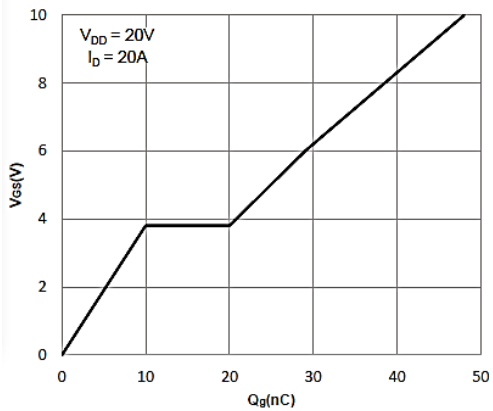


Figure 6: Capacitance Characteristics

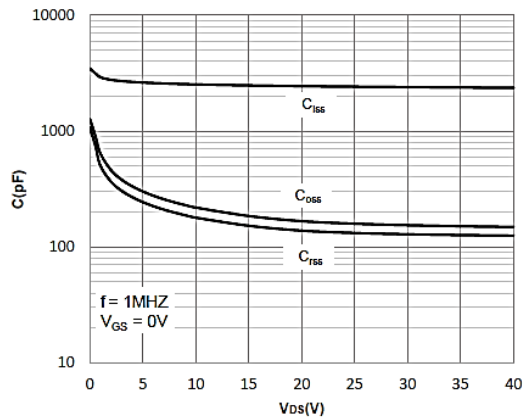


Figure 7: Normalized Breakdown voltage vs. Junction Temperature

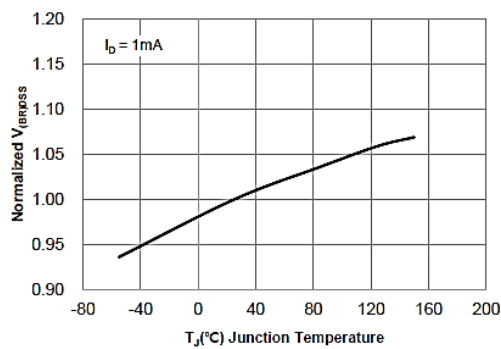


Figure 8: Normalized on Resistance vs. Junction Temperature

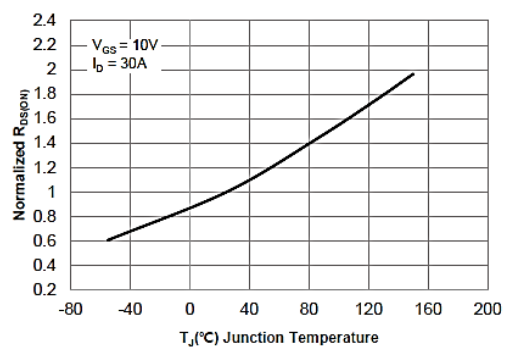




Figure 9: Maximum Safe Operating Area

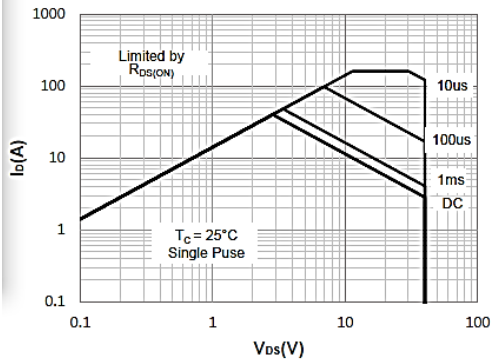


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

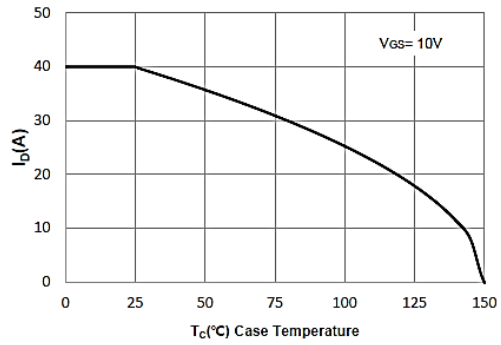


Figure 11: Normalized Maximum Transient Thermal Impedance

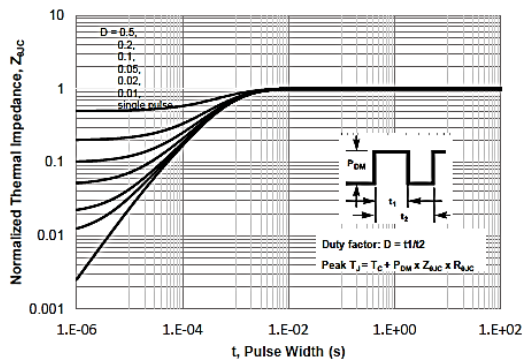
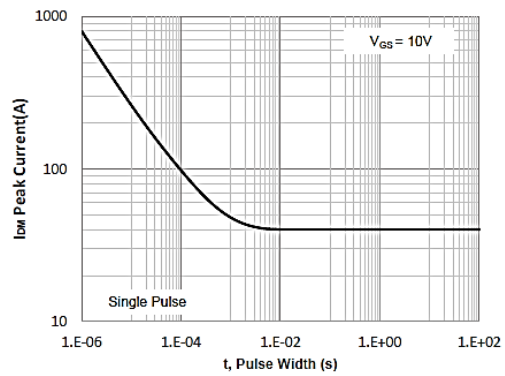


Figure 12: Peak Current Capacity





## Test Circuit

Figure 1: GateCharge Test Circuit & Waveform

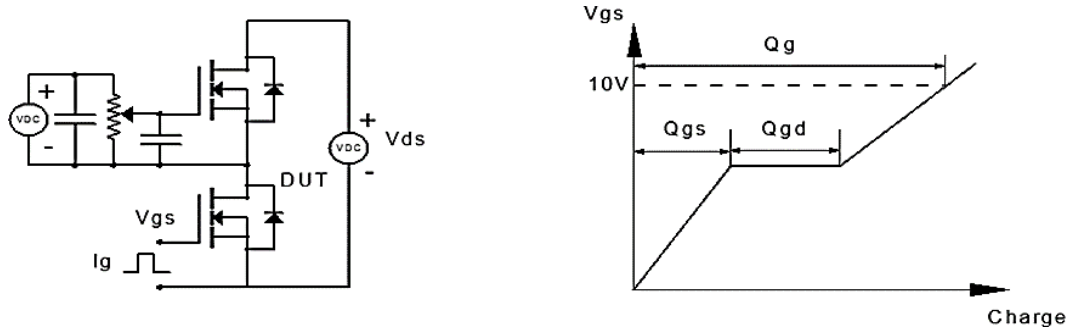


Figure 2: Resistive Switching Test Circuit & Waveform

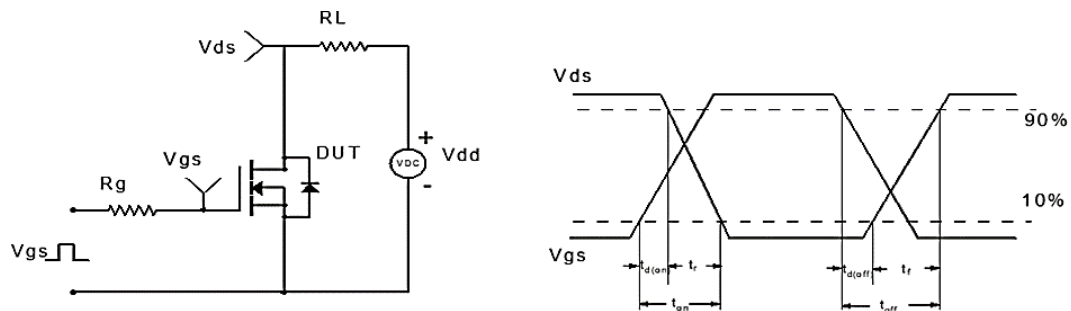


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

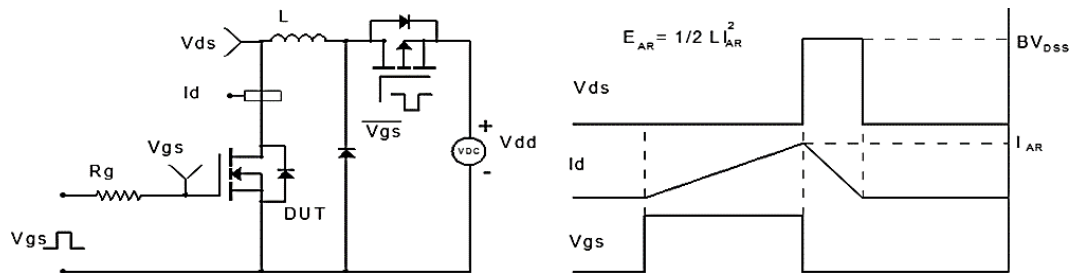
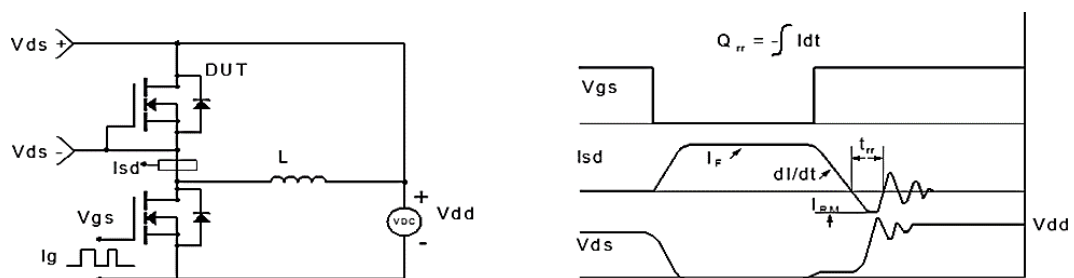
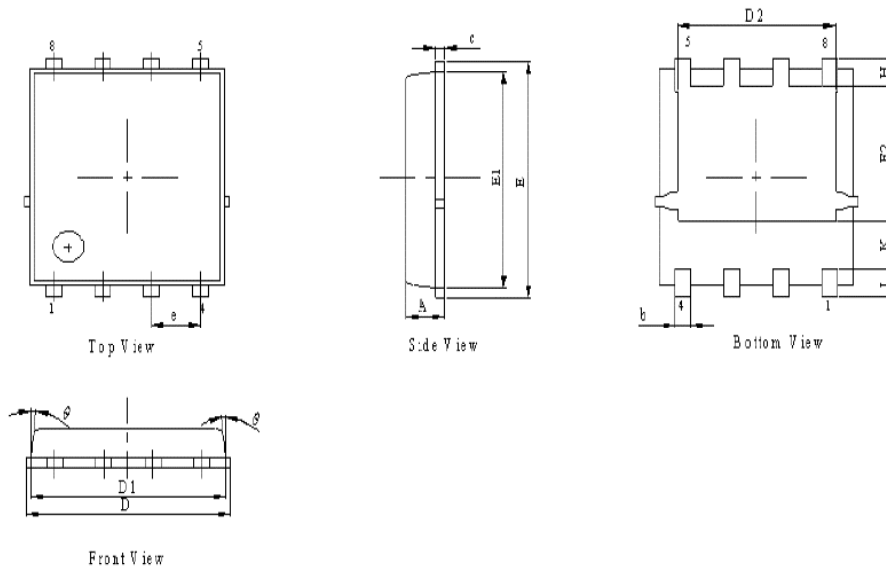


Figure 4: Diode Recovery Test Circuit & Waveform

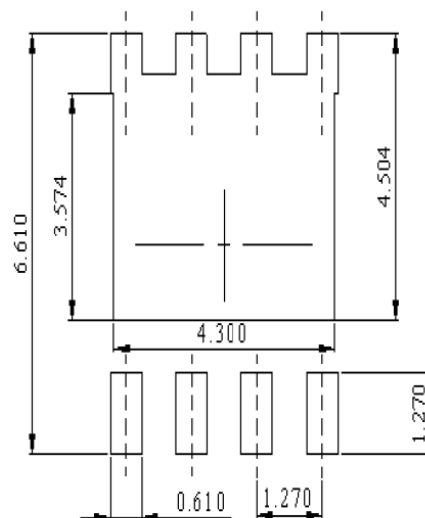




## Package Mechanical Data(PDFN 5x6-8L)



Symbol	Dimensions In Millimeters		
	Min.	NOM.	Max.
A	0.9	1	1.15
b	0.31	0.41	0.51
C	0.24	0.32	0.4
D	5	5.2	5.4
D1	4.95	5.05	5.15
D2	4	4.1	4.2
E	6.05	6.15	6.25
E1	5.5	5.6	5.7
E2	3.42	3.53	3.63
e	1.27 BSC		
H	0.6	0.7	0.8
L	0.5	0.7	0.8
K	1.23 BEF		
O			10



DIMENSIONS: MILLIMETERS



## Ordering information

Order Code	Package	V <sub>DS</sub> (V)	I <sub>D</sub> (A)	R <sub>DS(ON)</sub> ( mΩ )	
QNN70N04SD	PDFN 5x6-8	40	40	V <sub>GS</sub> =10V	7.6
				V <sub>GS</sub> =4.5V	11.5